Spansion® Analog and Microcontroller Products



The following document contains information on Spansion analog and microcontroller products. Although the document is marked with the name "Fujitsu", the company that originally developed the specification, Spansion will continue to offer these products to new and existing customers.

Continuity of Specifications

There is no change to this document as a result of offering the device as a Spansion product. Any changes that have been made are the result of normal document improvements and are noted in the document revision summary, where supported. Future routine revisions will occur when appropriate, and changes will be noted in a revision summary.

Continuity of Ordering Part Numbers

Spansion continues to support existing part numbers beginning with "MB". To order these products, please use only the Ordering Part Numbers listed in this document.

For More Information

Please contact your local sales office for additional information about Spansion memory, analog, and microcontroller products and solutions.

16-bit Microcontroller

CMOS

F²MC-16LX MB90335 Series

MB90337/F337/V330A

■ DESCRIPTION

The MB90335 series are 16-bit microcontrollers designed for applications, such as personal computer peripheral devices, that require USB communications. The USB feature supports not only 12-Mbps Function operation but also HOST operation. It is equipped with functions that are suitable for personal computer peripheral devices such as displays and audio devices, and control of mobile devices that support USB communications. While inheriting the AT architecture of the F²MC* family, the instruction set supports the C language and extended addressing modes and contains enhanced signed multiplication and division instructions as well as a substantial collection of improved bit manipulation instructions. In addition, long word processing is now available by introducing a 32-bit accumulator.

Note: F²MC is the abbreviation of FUJITSU Flexible Microcontroller.

■ FEATURES

- Clock
 - Built-in oscillation circuit and PLL clock frequency multiplication circuit
 - Oscillation clock
 - The main clock is the oscillation clock divided into 2 (for oscillation 6 MHz: 3 MHz)
 - · Clock for USB is 48 MHz
 - Machine clock frequency of 6 MHz, 12 MHz or 24 MHz selectable
 - Minimum execution time of instruction : 41.7 ns (6 MHz oscillation clock, 4-time multiplied : machine clock 24 MHz and at operating Vcc = 3.3 V)
- The maximum memory space: 16 Mbytes
- 24-bit addressing
- Bank addressing

(Continued)

For the information for microcontroller supports, see the following web site.

This web site includes the "Customer Design Review Supplement" which provides the latest cautions on system development and the minimal requirements to be checked to prevent problems before the system development.

http://edevice.fujitsu.com/micom/en-support/



• Instruction system

- · Data types: Bit, Byte, Word, Long word
- Addressing mode (23 types)
- Enhanced high-precision computing with 32-bit accumulator
- Enhanced Multiply/Divide instructions with sign and the RETI instruction

• Instruction system compatible with high-level language (C language) and multi-task

- Employing system stack pointer
- · Instruction set symmetry and barrel shift instructions
- Program Patch Function (2 address pointer)
- 4-byte instruction queue
- Interrupt function
 - Priority levels are programmable
 - 20 interrupts function

• Data transfer function

- Extended intelligent I/O service function (EI2OS): Maximum of 16 channels
- μDMAC : Maximum 16 channels

• Low Power Consumption Mode

- Sleep mode (with the CPU operating clock stopped)
- Time-base timer mode (with the oscillator clock and time-base timer operating)
- Stop mode (with the oscillator clock stopped)
- CPU intermittent operation mode (with the CPU operating at fixed intervals of set cycles)

Package

- LQFP-64P (FPT-64P-M23 : 0.65 mm pin pitch)
- Process : CMOS technology
- Operation guaranteed temperature: 40 °C to + 85 °C (0 °C to + 70 °C when USB is in use)

(Continued)

• Internal peripheral function (resource)

I/O port : Max 45 ports
Time-base timer : 1channel
Watchdog timer : 1 channel
16-bit reload timer : 1 channel

- Multi-functional timer
 - 8/16-bit PPG timer (8-bit × 4 channels or 16-bit × 2 channels) the period and duty of the output pulse are freely programmable.
 - 16-bit PWC timer: 1 channel
 Timer function and pulse width measurement function
- UART: 2 channels
 - Equipped with a full duplex (8-bit long) double buffer
 - Selectable asynchronous transfer or clock-synchronous serial (extended I/O serial) transfer.
- Extended I/O serial interface : 1 channel
- DTP/External interrupt circuit (8 channels)
 - Activate the extended intelligent I/O service by external interrupt input
 - Interrupt output by external interrupt input
- Delayed interrupt output module
 - · Outputs an interrupt request for task switching
- USB: 1 channel
 - USB function (supports USB Full Speed)
 - Supports Full Speed/Up to 6 endpoints can be specified.
 - Dual port RAM (supports FIFO mode).
 - Transfer type: Control, Interrupt, Bulk or Isochronous transfer possible
 - · USB HOST function
- I2C Interface: 1 channel
 - Supports Intel SM bus standards and Phillips I2C bus standards
 - Two-wire data transfer protocol specification
 - Master and slave transmission/reception

■ PRODUCT LINEUP

Part number	MB90V330A	MB90F337	MB90337	
Туре	For evaluation	Built-in Flash Memory	Built-in MASK ROM	
ROM capacity	No	64 Kb	ytes	
RAM capacity	28 Kbytes	4 Kbytes		
Emulator-specific power supply *	Used bit	_	-	
CPU functions	Number of basic instructions Minimum instruction execution time Addressing type Program Patch Function Maximum memory space	: 351 instructions : 41.7 ns / at oscillation of 6 MHz (When 4 times are used : Machine clock of 24 MHz) : 23 types : For 2 address pointers : 16 Mbytes		
Ports	I/O Ports(CMOS) Max 45 por	rts		
UART	Equipped with full-duplex dou Clock synchronous or asynch It can also be used for I/O se Built-in special baud-rate ger Built-in 2 channels	nronous operation selectable rial.	e.	
16-bit reload timer	16-bit reload timer operation Built-in 1 channel			
Multi-functional timer	8/16-bit PPG timer (8-bit mod 16-bit PWC timer × 1 channe		e × 2 channels)	
DTP/External interrupt	8 channels Interrupt factor : "L"→"H" edg	ge /"H"→"L" edge /"L" level /"	H" level selectable	
I ² C	1 channel			
Extended I/O serial interface	1 channel			
USB	1 channel USB function (supports USB USB HOST function	Full Speed)		
Withstand voltage of 5 V	8 ports (Excluding UTEST ar	nd I/O for I ² C)		
Low Power Consumption Mode	Sleep mode/Timebase timer	mode/Stop mode/CPU inter	mittent mode	
Process	CMOS			
Operating voltage Vcc	3.3 V \pm 0.3 V (at maximum m $$	nachine clock 24 MHz)		

^{*:} It is setting of Jumper switch (TOOL VCC) when Emulator (MB2147-01) is used. Please refer to the MB2147-01 or MB2147-20 hardware manual (3.3 Emulator-dedicated Power Supply Switching) about details.

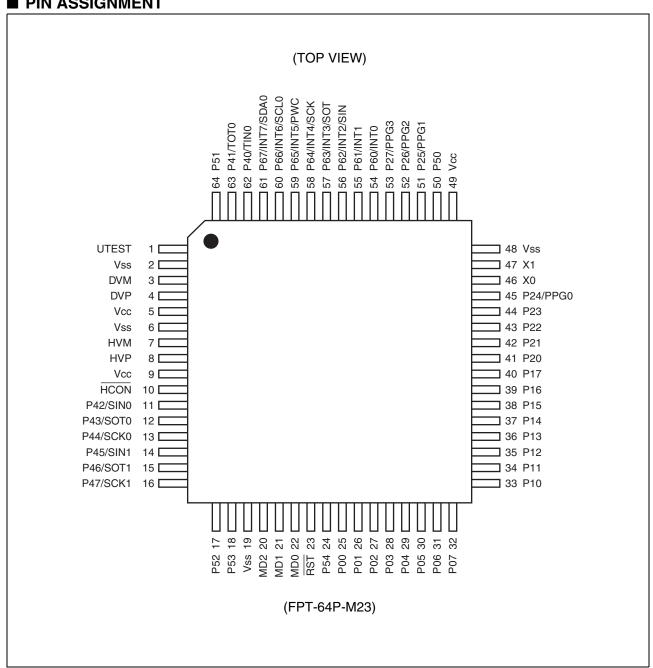
■ PACKAGES AND PRODUCT MODELS

Package	MB90337	MB90F337	MB90V330A
FPT-64P-M23 (LQFP)	0	0	×
PGA-299C-A01 (PGA)	X	×	0

 \circ : Yes \times : No

Note : See "■ PACKAGE DIMENSIONS" for details.

■ PIN ASSIGNMENT



■ PIN DESCRIPTION

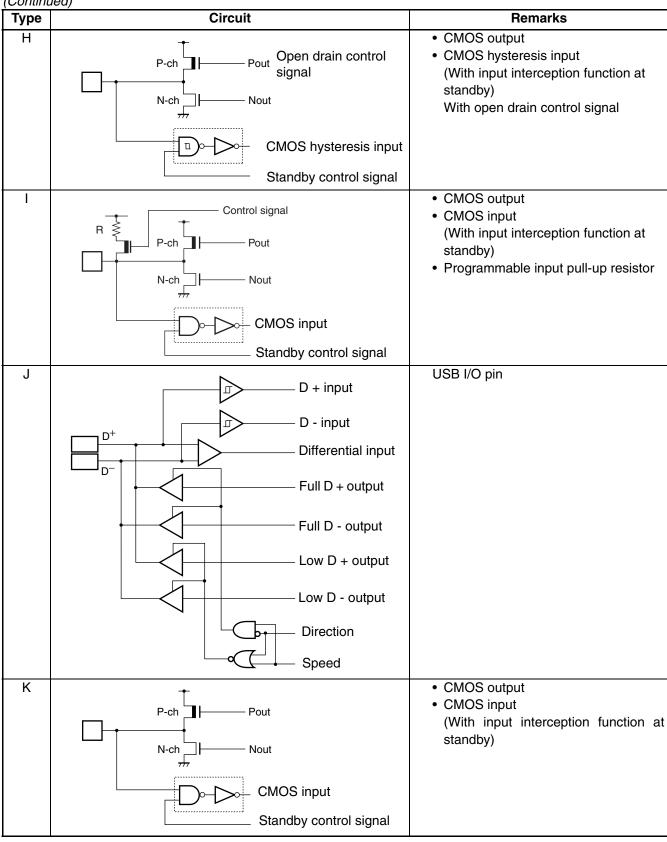
Pin no.	Pin name	I/O Circuit type*	Status at reset/ function	Function
46 , 47	X0, X1	А	Oscillation status	It is a terminal which connects the oscillator. When connecting an external clock, leave the X1 pin side unconnected.
23	RST	F	Reset input	External reset input pin.
25 to 32	P00 to P07	I		General purpose input/output port. The ports can be set to be added with a pull-up resistor (RD00 to RD07 = 1) by the pull-up resistor setting register (RDR0). (When the power output is set, it is invalid.)
33 to 40	P10 to P17	ı		General purpose input/output port. The ports can be set to be added with a pull-up resistor (RD10 to RD17 = 1) by the pull-up resistor setting register (RDR1). (When the power output is set, it is invalid.)
41 to 44	P20 to P23	D		General purpose input/output port.
45	P24	D		General purpose input/output port.
45	PPG0			Functions as output pins of PPG timers ch.0.
51 to 53	P25 to P27	D		General purpose input/output port.
31 10 30	PPG1 to PPG3			Functions as output pins of PPG timers ch.1 to ch.3.
62	P40	Н		General purpose input/output port.
02	TIN0			Function as event input pin of 16-bit reload timer.
63	P41	Н		General purpose input/output port.
	TOT0		Port input	Function as output pin of 16-bit reload timer.
11	P42	Н	(Hi-Z)	General purpose input/output port.
	SIN0			Functions as a data input pin for UART ch.0.
12	P43	Н		General purpose input/output port.
,,_	SOT0			Functions as a data output pin for UART ch.0.
13	P44	Н		General purpose input/output port.
.0	SCK0			Functions as a clock I/O pin for UART ch.0.
14	P45	н		General purpose input/output port.
	SIN1			Functions as a data input pin for UART ch.1.
15	P46	Н		General purpose input/output port.
10	SOT1			Functions as a data output pin for UART ch.1.
16	P47	Н		General purpose input/output port.
	SCK1			Functions as a clock I/O pin for UART ch.1.
50	P50	K		General purpose input/output port.
64	P51	K		General purpose input/output port.
17, 18	P52, P53	K		General purpose input/output port.
24	P54	K		General purpose input/output port.

(Continued) Pin no.	Pin name	I/O Circuit type*	Status at reset/ function	Function	
	P60, P61	0		General purpose input/output port (withstand voltage of 5 V).	
54, 55	INT0, INT1	С		Functions as the input pin for external interrupt ch.0 and ch.1.	
	P62			General purpose input/output port (withstand voltage of 5 V).	
56	INT2	С		Functions as the input pin for external interrupt ch.2.	
	SIN			Data input pin for extended I/O serial interface.	
	P63			General purpose input/output port (withstand voltage of 5 V).	
57	INT3	С		Functions as the input pin for external interrupt ch.3.	
	SOT			Data output pin for extended I/O serial interface.	
	P64			General purpose input/output port (withstand voltage of 5 V).	
58	INT4	С		Functions as the input pin for external interrupt ch.4.	
	SCK		Port input	Clock I/O pin for extended I/O serial interface.	
	P65		(Hi-Z)	General purpose input/output port (withstand voltage of 5 V).	
59	59 INT5		,	Functions as the input pin for external interrupt ch.5.	
	PWC			Functions as the PWC input pin.	
	P66			General purpose input/output port (withstand voltage of 5 V).	
	INT6	С		Functions as the input pin for external interrupt ch.6.	
60	SCL0			Functions as the input/output pin for I ² C interface clock. The port output must be placed in Hi-Z state during I ² C interface operation.	
	P67			General purpose input/output port (withstand voltage of 5 V).	
61	INT7	С		Functions as the input pin for external interrupt ch.7.	
01	SDA0			Functions as the I ² C interface data input/output pin. The port output must be placed in Hi-Z state during I ² C interface operation.	
1	UTEST	С	UTEST input	USB test pin. Connect this to a pull-down resistor during normal usage.	
3	DVM	J		USB function D – pin.	
4	DVP	J	USB input	USB function D + pin.	
7	HVM	J	(SUSPEND)	USB HOST D – pin.	
8	HVP	J		USB HOST D + pin.	
10	HCON	Е	High output	External pull-up resistor connection pin.	
21, 22	MD1, MD0	В	Mode input	Input pin for selecting operation mode.	
20	MD2	G	ivioue iriput	input pin for selecting operation mode.	
5, 9, 49	Vcc		Power	Power supply pin.	
2, 6, 19, 48	Vss	_	supply	Power supply pin (GND).	

^{* :} For circuit information, refer to "■ I/O CIRCUIT TYPE".

■ I/O CIRCUIT TYPE

Туре	Circuit	Remarks
А	X1 X0 X0 Standby control signal	 Oscillation feedback resistor of approx. 1 MΩ With standby control
В	CMOS hysteresis input	CMOS hysteresis input
С	N-ch Nout CMOS hysteresis input Standby control signal	CMOS hysteresis input N-ch open drain output
D	P-ch Pout N-ch Nout CMOS hysteresis input Standby control signal	CMOS output CMOS hysteresis input (With input interception function at standby) Notes: Share one output buffer because both output of I/O port and internal resource are used. Share one input buffer because both input of I/O port and internal resource are used.
E	P-ch Pout N-ch Nout	CMOS output
F	CMOS hysteresis input	CMOS hysteresis input with pull-up resistor of approx. 50 kΩ
G	CMOS hysteresis input	 CMOS hysteresis input with pull-down resistor of approx. 50 kΩ Flash product is not provided with pull-down resistor.



■ HANDLING DEVICES

1. Preventing latch-up and turning on power supply

latch-up may occur on CMOS IC under the following conditions:

- If a voltage higher than Vcc or lower than Vss is applied to input and output pins.
- A voltage higher than the rated voltage is applied between Vcc and Vss.

When latch-up occurs, power supply current increases rapidly and might thermally damage elements. When using CMOS IC, take great care to prevent the occurrence of latch-up.

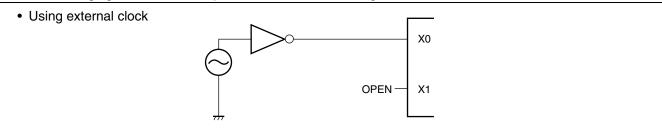
2. Treatment of unused pins

Leaving unused input pins unconnected can cause abnormal operation or latch-up, leading to permanent damage. Unused input pins should always be pulled up or down through resistance of at least 2 $k\Omega$. Any unused input/output pins may be set to output mode and left open, or set to input mode and treated the same as unused input pins. If there is unused output pin, make it to open.

3. About the attention when the external clock is used

Even when using an external clock signal, an oscillation stabilization delay is applied after a power-on reset or when recovering from sub-clock or stop mode. When suing an external clock, 25 MHz should be the upper frequency limit.

The following figure shows a sample use of external clock signals.



4. Treatment of power supply pins (Vcc/Vss)

In products with multiple V_{CC} or V_{SS} pins, the pins of the same potential are internally connected in the device to avoid abnormal operations including latch-up. However, you must connect the pins to external power supply and a ground line to lower the electro-magnetic emission level, to prevent abnormal operation of strobe signals caused by the rise in the ground level, and to conform to the total output current rating.

Moreover, connect the current supply source with the Vcc and Vss pins of this device at the low impedance.

It is also advisable to connect a ceramic bypass capacitor of approximately 0.1 μ F between V_{CC} and V_{SS} pins near this device.

5. About crystal oscillator circuit

Noise near the X0 and X1 pins may cause the device to malfunction. Design the printed circuit board so that X0, X1, the crystal oscillator (or ceramic oscillator), and the bypass capacitor to ground are located as close to the device as possible.

It is strongly recommended to design the PC board artwork with the X0 and X1 pins surrounded by ground plane because stable operation can be expected with such a layout.

Please ask the crystal maker to evaluate the oscillational characteristics of the crystal and this device.

6. Caution on Operations during PLL Clock Mode

On this microcontroller, if in case the crystal oscillator breaks off or an external reference clock input stops while the PLL clock mode is selected, a self-oscillator circuit contained in the PLL may continue its operation at its self-running frequency. However, Fujitsu will not guarantee results of operations if such failure occurs.

7. Stabilization of supply voltage

A sudden change in the supply voltage may cause the device to malfunction even within the V_{CC} supply voltage operating range. For stabilization reference, the supply voltage should be stabilized so that V_{CC} ripple variations (peak-to-peak value) at commercial frequencies (50 MHz to 60 MHz) fall below 10% of the standard V_{CC} supply voltage and the transient regulation does not exceed 0.1 V/ms at temporary changes such as power supply switching.

8. Writing to flash memory

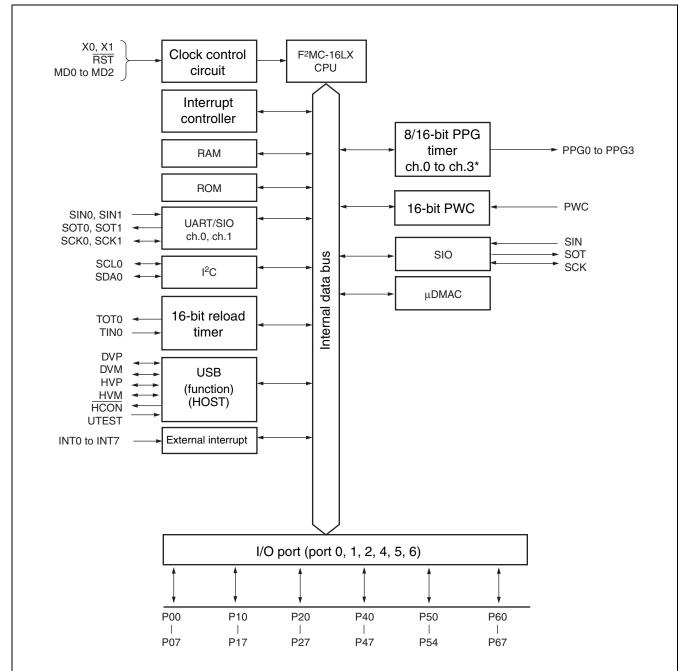
For serial writing to flash memory, always make sure that the operating voltage Vcc is between 3.13 V and 3.6 V. For normal writing to flash memory, always make sure that the operating voltage Vcc is between 3.0 V and 3.6 V.

9. Serial communication

There is a possibility to receive wrong data due to noise or other causes on the serial communication. Therefore, design a printed circuit board so as to avoid noise.

Consider receiving of wrong data when designing the system. For example, apply a checksum to detect an error. If an error is detected, retransmit the data.

■ BLOCK DIAGRAM



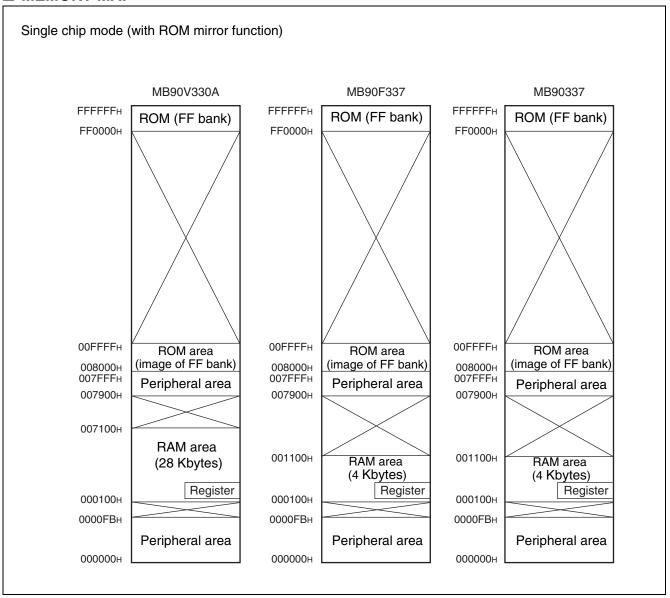
^{*:} Channel for use in 8-bit mode. 2 channels (ch.1, ch.3) are used in 16-bit mode.

Note: I/O ports share pins with peripheral function (resources) .

For details, refer to "■ PIN ASSIGNMENT" and "■ PIN DESCRIPTION".

Note also that pins used for peripheral function (resources) cannot serve as I/O ports.

■ MEMORY MAP

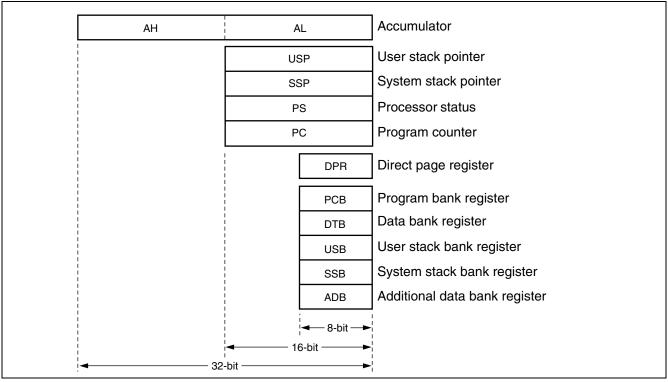


Notes: • When the ROM mirror function register has been set, the mirror image data at higher addresses ("FF8000H to FFFFFFH") of bank FF is visible from the higher addresses ("008000H to 00FFFFH") of bank 00.

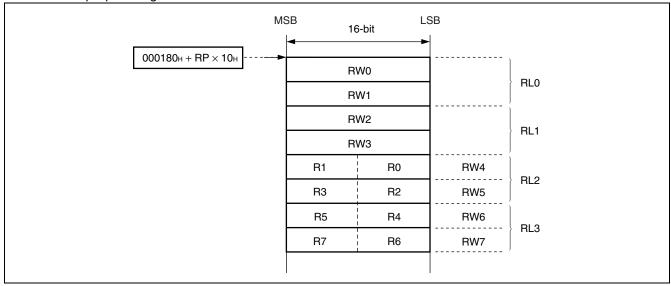
- The ROM mirror function is effective for using the C compiler small model.
- The lower 16-bit addresses of bank FF are equivalent to those of bank 00. Since the ROM area in bank FF exceeds 48 Kbytes, however, the mirror image of all the data in the ROM area cannot be reproduced in bank 00.
- When the C compiler small model is used, the data table mirror image can be shown at "008000H to 00FFFFH" by storing the data table at "FF8000H to FFFFFFH".
 Therefore, data tables in the ROM area can be referred without declaring the far addressing with the pointer.

■ F²MC-16L CPU PROGRAMMING MODEL

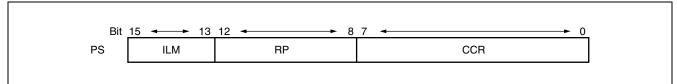
Dedicated register



· General purpose registers



Processor status



■ I/O MAP

Address	Register abbreviation	Register	Read/ Write	Resource name	Initial Value			
000000н	PDR0	Port 0 Data Register	R/W	Port 0	XXXXXXXXB			
000001н	PDR1	Port 1 Data Register	R/W	Port 1	XXXXXXXXB			
000002н	PDR2	Port 2 Data Register	R/W	Port 2	XXXXXXXX			
000003н		Prohibited						
000004н	PDR4	Port 4 Data Register	R/W	Port 4	XXXXXXXX			
000005н	PDR5	Port 5 Data Register	R/W	Port 5	ХХХХХ в			
000006н	PDR6	Port 6 Data Register	R/W	Port 6	XXXXXXXX			
000007н to 00000Fн		Prohibite	ed					
000010н	DDR0	Port 0 Direction Register	R/W	Port 0	0 0 0 0 0 0 0 0 _B			
000011н	DDR1	Port 1 Direction Register	R/W	Port 1	0 0 0 0 0 0 0 0 _B			
000012н	DDR2	Port 2 Direction Register	R/W	Port 2	0 0 0 0 0 0 0 0 _B			
000013н		Prohibite	ed	1	l			
000014н	DDR4	Port 4 Direction Register	R/W	Port 4	0 0 0 0 0 0 0 0 _B			
000015н	DDR5	Port 5 Direction Register	R/W	Port 5	00000B			
000016н	DDR6	Port 6 Direction Register	R/W	Port 6	0 0 0 0 0 0 0 0в			
000017н		Drobibite	. d					
to 00001Ан		Prohibite	eu					
00001Вн	ODR4	Port 4 Output Pin Register	R/W	Port 4 (Open-drain control)	0 0 0 0 0 0 0 0в			
00001Сн	RDR0	Port 0 Pull-up Resistance Register	R/W	Port 0 (PULL-UP)	0 0 0 0 0 0 0 0в			
00001Dн	RDR1	Port 1 Pull-up Resistance Register	R/W	Port 1 (PULL-UP)	0 0 0 0 0 0 0 0 _B			
00001Ен		Prohibite	rq					
00001Fн		Tomste	, G					
000020н	SMR0	Serial Mode Register 0	R/W		0 0 1 0 0 0 0 0в			
000021н	SCR0	Serial Control Register 0	R/W		00000100в			
000022н	SIDR0	Serial Input Data Register 0	R	UART0	XXXXXXXX			
	SODR0	Serial Output Data Register 0	W					
000023н	SSR0	Serial Status Register 0	R/W		0 0 0 0 1 0 0 0в			
000024н	UTRLR0	UART Prescaler Reload Register 0	R/W	Communication	0 0 0 0 0 0 0 0в			
000025н	UTCR0	UART Prescaler Control Register 0	R/W	Prescaler (UART0)	0 0 0 0 - 0 0 0 _B			
000026н	SMR1	Serial Mode Register 1	R/W	UART1	0 0 1 0 0 0 0 0в			
000027н	SCR1	Serial Control Register 1	R/W		0 0 0 0 0 1 0 0в			
000028н	SIDR1	Serial Input Data Register 1	R		XXXXXXXXB			
OUUUZUH	SODR1	Serial Output Data Register 1	W		XXXXXXXX			
000029н	SSR1	Serial Status Register 1	R/W		0 0 0 0 1 0 0 0в			

Address	Register abbreviation	Register	Read/ Write	Resource name	Initial Value
00002Ан	UTRLR1	UART Prescaler Reload Register 1	R/W	Communication	0 0 0 0 0 0 0 0в
00002Вн	UTCR1	UART Prescaler Control Register 1	R/W	Prescaler (UART1)	0 0 0 0 - 0 0 0 _B
00002Сн				L	•
to		Prohibited			
00003Вн		<u> </u>		1	
00003Сн	ENIR	DTP/Interrupt Enable Register	R/W		0 0 0 0 0 0 0 0в
00003Dн	EIRR	DTP/Interrupt source Register	R/W	DTP/External	0 0 0 0 0 0 0 0в
00003Ен	ELVR	Request Level Setting Register Lower	R/W	interrupt	0 0 0 0 0 0 0 0в
00003Fн		Request Level Setting Register Upper	R/W		0 0 0 0 0 0 0 0в
000040н		-			
to 000045н		Prohibited			
000046н	PPGC0	PPG0 Operation Mode Control Register	R/W	PPG ch.0	0Х0 0 0ХХ1в
000047н	PPGC1	PPG1 Operation Mode Control Register	R/W	PPG ch.1	0Х0 0 0 0 0 1в
000048н	PPGC2	PPG2 Operation Mode Control Register	R/W	PPG ch.2	0Х0 0 0ХХ1в
000049н	PPGC3	PPG3 Operation Mode Control Register	R/W	PPG ch.3	0Х0 0 0 0 0 1в
00004Ан					
00004Вн		Prohibited			
00004Сн	PPG01	PPG0 and PPG1 Output Control Register	R/W	PPG ch.0/ch.1	0 0 0 0 0 0ХХв
00004Dн		Prohibited			
00004Ен	PPG23	PPG2 and PPG3 Output Control Register	R/W	PPG ch.2/ch.3	0 0 0 0 0 0 XX _B
00004Fн					
to 000057н		Prohibited			
000057н		T			ХХХХО О О Ов
000059н	SMCS	Serial Mode Control Status Register	R/W	Extended Serial	0 0 0 0 0 0 1 0 _B
000059н	SDR	Serial Data Register	R/W	I/O	XXXXXXXX
00003AH		Communication Prescaler Control		Communication	
00005Вн	SDCR	Register	R/W	Prescaler	0ХХХО О О Ов
00005Сн	PWCSR	PWC Control Status Register	R/W		0 0 0 0 0 0 0 0в
00005Dн	1 WOOIT	1 WO Control Status Hegister	1 I/ V V	16 bit	0 0 0 0 0 0 0 X _B
00005Ен	PWCR	PWC Data Buffer Register	R/W	16-bit PWC Timer	0 0 0 0 0 0 0 0в
00005Fн	FVVCH	rwc Data Bullet negister	□/ V V	1 110 111101	0 0 0 0 0 0 0 0в
000060н	DIVR	PWC Dividing Ratio Control Register	R/W		О Ов
000061н		Prohibited			
000062н	TMCSR0	Timer Control Status Register	R/W		0 0 0 0 0 0 0 0в
000063н	TWOSHO	Timer Control Status negister	□/ V V		XXXX 0 0 0 0 _B
000064н	TMR0	16-bit Timer Register Lower	R	16-bit Reload	XXXXXXXX
000004H	TMRLR0	16-bit Reload Register Lower	W	Timer	XXXXXXXXB
000065н	TMR0	16-bit Timer Register Upper	R		XXXXXXXXB
НСООООО	TMRLR0	16-bit Reload Register Upper	W		XXXXXXXXB
					(Continued)

Address	Register abbreviation	Register	Read/ Write	Resource name	Initial Value
000066н to 00006Ен		Prohibited		•	
00006Fн	ROMM	ROM Mirroring Function Selection Register	W	ROM Mirror Function Selection Module	1 1в
000070н	IBSR0	I ² C Bus Status Register	R		00000000
000071н	IBCR0	I ² C Bus Control Register	R/W		0 0 0 0 0 0 0 0в
000072н	ICCR0	I ² C Bus Clock Control Register	R/W	I ² C Bus Interface	XX 0 XXXXXB
000073н	IADR0	I ² C Bus Address Register	R/W		XXXXXXXX
000074н	IDAR0	I ² C Bus Data Register	R/W		XXXXXXXX
000075н to 00009Ан		Prohibited			
00009Вн	DCSR	DMA Descriptor Channel Specification Register	R/W	μDMAC	0 0 0 0 0 0 0 0 0в
00009Сн	DSRL	DMA Status Register Lower	R/W		0 0 0 0 0 0 0 0в
00009Dн	DSRH	DMA Status Register Upper	R/W		0 0 0 0 0 0 0 0в
00009Ен	PACSR	Program Address Detection Control Status Register	R/W	Address Match Detection	0 0 0 0 0 0 0 0 0в
00009Fн	DIRR	Delayed Interrupt Source generate/ release Register	R/W	Delayed Interrupt	Ов
0000А0н	LPMCR	Low Power Consumption Mode Control Register	R/W	Low Power Consumption control circuit	00011000в
0000А1н	CKSCR	Clock Selection Register	R/W	Clock	11111100в
0000А2н		Prohibited			
0000АЗн		FTOTIIbited			
0000А4н	DSSR	DMA Stop Status Register	R/W	μDMAC	0 0 0 0 0 0 0 0 _B
0000A5н to 0000A7н		Prohibited			
0000А8н	WDTC	Watchdog Timer Control Register	R/W	Watchdog Timer	X - XXX 1 1 1 _B
0000А9н	TBTC	Time-base Timer Control Register	R/W	Time-base Timer	1 0 0 1 0 Ов
0000ААн		D. J. P. J.	1	ı	ı
0000АВн		Prohibited			
0000АСн	DERL	DMA Enable Register Lower	R/W		0 0 0 0 0 0 0 0 _B
0000АDн	DERH	DMA Enable Register Upper	R/W	μDMAC	0 0 0 0 0 0 0 0 _B
0000АЕн	FMCS	Flash Memory Control Status Register	R/W	Flash Memory I/F	0 0 0 X 0 0 0 0 _B
0000АГн		Prohibited		1	1

Address	Register abbreviation	Register	Read/ Write	Resource name	Initial Value
0000В0н	ICR00	Interrupt Control Register 00	R/W		00000111В
0000В1н	ICR01	Interrupt Control Register 01	R/W	1	00000111в
0000В2н	ICR02	Interrupt Control Register 02	R/W		00000111в
0000ВЗн	ICR03	Interrupt Control Register 03	R/W		00000111в
0000В4н	ICR04	Interrupt Control Register 04	R/W		00000111в
0000В5н	ICR05	Interrupt Control Register 05	R/W		00000111в
0000В6н	ICR06	Interrupt Control Register 06	R/W		00000111в
0000В7н	ICR07	Interrupt Control Register 07	R/W	Interrupt	00000111в
0000В8н	ICR08	Interrupt Control Register 08	R/W	Controller	00000111в
0000В9н	ICR09	Interrupt Control Register 09	R/W		00000111в
0000ВАн	ICR10	Interrupt Control Register 10	R/W		00000111в
0000ВВн	ICR11	Interrupt Control Register 11	R/W		00000111в
0000ВСн	ICR12	Interrupt Control Register 12	R/W		00000111в
0000ВDн	ICR13	Interrupt Control Register 13	R/W		00000111в
0000ВЕн	ICR14	Interrupt Control Register 14	R/W		00000111в
0000ВFн	ICR15	Interrupt Control Register 15	R/W		00000111в
0000С0н	HCNT0	Host Control Register 0	R/W		0 0 0 0 0 0 0 0 _B
0000С1н	HCNT1	Host Control Register 1	R/W		0000001в
0000С2н	HIRQ	Host Interruption Register	R/W		0 0 0 0 0 0 0 0 _B
0000СЗн	HERR	Host Error Status Register	R/W		0000011в
0000С4н	HSTATE	Host State Status Register	R/W		XX 0 1 0 0 1 0 _B
0000С5н	HFCOMP	SOF Interrupt FRAME Compare Register	R/W		0 0 0 0 0 0 0 0в
0000С6н			R/W	LICDLICCT	0 0 0 0 0 0 0 0 _B
0000С7н	HRTIMER	Retry Timer Setting Register	R/W	USB HOST	0 0 0 0 0 0 0 0 _B
0000С8н			R/W		XXXXXX 0 0 _B
0000С9н	HADR	Host Address Register	R/W		X 0 0 0 0 0 0 0 _B
0000САн	HEOF	EOF Setting Register	R/W		0 0 0 0 0 0 0 0в
0000СВн	TILOI	LOT Setting Hegister	R/W		XX 0 0 0 0 0 0 _B
0000ССн	HFRAME	FRAME Setting Register	R/W		0 0 0 0 0 0 0 0в
0000СDн	HERAIVIE	Phanic Setting negister	R/W	7	XXXXX 0 0 0 _B
0000СЕн	HTOKEN	Host Token End Point Register	R/W	<u> </u>	0 0 0 0 0 0 0 0в
0000СFн		Prohibited	t		
0000D0н	UDCC	UDC Control Register	R/W	USB Function	1 0 1 0 0 0 0 0в
0000D1н	ODCC	ODO CONTION REGISTER	R/W	- USB FUNCTION	0 0 0 0 0 0 0 0в

	Register		Read/		
Address	abbreviation	Register	Write	Resource name	Initial Value
0000D2н	EP0C	EP0 Control Register	R/W		0 1 0 0 0 0 0 0в
0000Д3н	LI OC	Li o Control Negister	R/W		XXXX 0 0 0 0 _B
0000Дн	EP1C	EP1 Control Register	R/W		0 0 0 0 0 0 0 0 _B
0000Д5н	EFIC	Er i Contiol negister	R/W		01100001в
0000Д6н	EP2C	EP2 Control Register	R/W		0 1 0 0 0 0 0 0в
0000D7н	LI 20	Li 2 Control Negister	R/W		0 1 1 0 0 0 0 0в
0000D8н	EP3C	EP3 Control Register	R/W		0 1 0 0 0 0 0 0в
0000D9н	LI 30	Li o Control Flegister	R/W		0 1 1 0 0 0 0 0в
0000Дн	EP4C	EP4 Control Register	R/W		0 1 0 0 0 0 0 0в
0000ДВн	LI 40	Li 4 Control Negister	R/W		0 1 1 0 0 0 0 0в
0000DСн	EP5C	EP5 Control Register	R/W		0 1 0 0 0 0 0 0в
0000DDн	LI 30	Li 3 Control Flegister	R/W		0 1 1 0 0 0 0 0в
0000ДЕн	TMSP	Time Stamp Register	R		0 0 0 0 0 0 0 0в
0000DFн	TIVIOI	Time Stamp Register	R		XXXXX0 0 0 _B
0000Е0н	UDCS	UDC Status Register	R/W		XX0 0 0 0 0 0 _B
0000Е1н	UDCIE	UDC Interrupt Enable Register	R/W		0 0 0 0 0 0 0 0в
0000Е2н	EP0IS	EP0I Status Register	R/W		XXXXXXXXB
0000ЕЗн			R/W	USB Function	1 0 XXX 1 XX _B
0000Е4н	EP0OS	EP0O Status Register	R/W, R		0 XXXXXXXB
0000Е5н	LI 000		R/W		1 0 0 XX 0 0 Ов
0000Е6н	EP1S	EP1 Status Register	R		XXXXXXXXB
0000Е7н	LI 10	EFT Status negister	R/W		1 0 0 0 0 0 0 X _B
0000Е8н	EP2S	EP2 Status Register	R		XXXXXXXXB
0000Е9н	Li 20	El 2 dialas riegister	R/W		1 0 0 0 0 0 0 0 _B
0000ЕАн	EP3S	EP3 Status Register	R		XXXXXXXXB
0000ЕВн	21 00	Er o Gialdo Flegiolei	R/W		1 0 0 0 0 0 0 0 _B
0000ЕСн	EP4S	EP4 Status Register	R		XXXXXXXXB
0000EDн		Li i dialagi neglotor	R/W		1 0 0 0 0 0 0 0 _B
0000ЕЕн	EP5S	EP5 Status Register	R		XXXXXXXXB
0000ЕГн	2. 00	E. o Giaido Fioglotoi	R/W		1 0 0 0 0 0 0 0 _B
0000F0н	EP0DT	EP0 Data Register	R/W		XXXXXXXXB
0000F1н	21 00 1	Li o Bata Hogistoi	R/W		XXXXXXXXB
0000F2н	EP1DT	EP1 Data Register	R/W		XXXXXXXXB
0000F3н		Li i Data riegistei	R/W		XXXXXXXXB
0000F4н	EP2DT	EP2 Data Register	R/W		XXXXXXXXB
0000F5н			R/W		XXXXXXXXB
0000F6н	EP3DT	EP3 Data Register	R/W		XXXXXXXXB
0000F7н		E. o Data Hogistol	R/W		XXXXXXXXB
0000F8н	EP4DT	EP4 Data Register	R/W]	XXXXXXXXB
0000F9н		L Data Hogistor	R/W		(Continued)

Address	Register abbreviation	Register	Read/ Write	Resource name	Initial Value
0000F A н	EP5DT	EDE Data Bagistar	R/W	USB Function	XXXXXXXXB
0000FBн	EFSDT	EP5 Data Register	R/W	- USB Function	XXXXXXXX
0000FCн to 0000FFн		Prohibited	d		
000100н to 001100н		RAM Area	a		
001FF0н		Program Address Detection Register ch.0 Lower	R/W		XXXXXXXX
001FF1н	PADR0	Program Address Detection Register ch.0 Middle	R/W	Address Match Detection	XXXXXXXX
001FF2н		Program Address Detection Register ch.0 Upper	R/W		XXXXXXXX
001FF3н		Program Address Detection Register ch.1 Lower	R/W		XXXXXXXX
001FF4н	PADR1	Program Address Detection Register ch.1 Middle	R/W		XXXXXXXX
001FF5н		Program Address Detection Register ch.1 Upper	R/W		XXXXXXXX
007900н	PRLL0	PPG Reload Register Lower ch.0	R/W	DDO at a	XXXXXXXXB
007901н	PRLH0	PPG Reload Register Upper ch.0	R/W	PPG ch.0	XXXXXXXXB
007902н	PRLL1	PPG Reload Register Lower ch.1	R/W	PPG ch.1	XXXXXXXX
007903н	PRLH1	PPG Reload Register Upper ch.1	R/W	PPG CII. I	XXXXXXXXB
007904н	PRLL2	PPG Reload Register Lower ch.2	R/W	PPG ch.2	XXXXXXXX
007905н	PRLH2	PPG Reload Register Upper ch.2	R/W	PPG CII.2	XXXXXXXXB
007906н	PRLL3	PPG Reload Register Lower ch.3	R/W	PPG ch.3	XXXXXXXXB
007907н	PRLH3	PPG Reload Register Upper ch.3	R/W	PPG CII.3	XXXXXXXXB
007908н to 00790Вн		Prohibited	d		
00790Сн	FWR0	Flash Memory Program Control Register 0	R/W	Flash	0 0 0 0 0 0 0 0 0в
00790Dн	FWR1	Flash Memory Program Control Register 1	R/W	Flash	0 0 0 0 0 0 0 0 0
00790Ен	SSR0	Sector Conversion Setting Register	R/W	Flash	0 0 XXXXX0B
00790Fн to 00791Fн		Prohibited	t		(Continued

(Continued)

Address	Register abbreviation	Register	Read/ Write	Resource name	Initial Value
007920н	DBAPL	DMA Buffer Address Pointer Lower 8-bit	R/W		XXXXXXXX
007921н	DBAPM	DMA Buffer Address Pointer Middle 8-bit	R/W		XXXXXXXXB
007922н	DBAPH	DMA Buffer Address Pointer Upper 8-bit	R/W		XXXXXXXXB
007923н	DMACS	DMA Control Register	R/W		XXXXXXXXB
007924н	DIOAL	DMA I/O Register Address Pointer Lower 8-bit	R/W	μDMAC	XXXXXXX
007925н	DIOAH	DMA I/O Register Address Pointer Upper 8-bit	R/W		XXXXXXX
007926н	DDCTL	DMA Data Counter Lower 8-bit	R/W		XXXXXXXXB
007927н	DDCTH	DMA Data Counter Upper 8-bit	R/W		XXXXXXXXB
007928н to 007FFFн		Prohibited			

• Explanation on read/write

R/W : Readable and Writable

R: Read only W: Write only

• Explanation of initial values

0 : Initial value is "0".1 : Initial value is "1".

X : Initial value is undefined.

- : Initial value is undefined (None).

Note: No I/O instruction can be used for registers located between 007900H and 007FFFH.

■ INTERRUPT SOURCES, INTERRUPT VECTORS, AND INTERRUPT CONTROL REGISTERS

Interrupt source	El ² OS	μ DMAC	Int	terrupt	vector	Interruj reg	Prior	
•	support	[]	Number*1 Address		ICR	Address		
Reset	×	×	#08	08н	FFFFDCH			Higl
INT 9 instruction	×	×	#09	09н	FFFFD8 _H	_	_	A
Exceptional treatment	×	×	#10	0Ан	FFFFD4 _H	_	_	Ī
USB Function1	×	0, 1	#11	0Вн	FFFFD0 _H	ICDOO	0000В0н	
USB Function2	×	2 to 6*2	#12	0Сн	FFFFCCH	ICR00	ООООВОН	
USB Function3	×	×	#13	0Дн	FFFFC8 _H	ICR01	0000В1н	
USB Function4	×	×	#14	0Ен	FFFFC4 _H	ICHUI	ООООБІН	
USB HOST1	×	×	#15	0Fн	FFFFC0 _H	ICR02	0000В2н	
USB HOST2	×	×	#16	10н	FFFFBCH	ICHU2	0000 D ZH	
l ² C ch.0	×	×	#17	11н	FFFFB8 _H	ICBOS	000000	
DTP/External interrupt ch.0/ch.1	0	×	#18	12н	FFFFB4 _H	ICR03	0000ВЗн	
No		_	#19	13н	FFFFB0 _H	ICD04	0000001	
DTP/External interrupt ch.2/ch.3	0	×	#20	14н	FFFFAC⊢	ICR04	0000В4н	
No		_	#21	15н	FFFFA8 _H	ICDOL	00000	
DTP/External interrupt ch.4/ch.5	0	×	#22	16н	FFFFA4 _H	ICR05	0000В5н	
PWC/Reload timer ch.0	Δ	14	#23	17н	FFFFA0 _H	IODOC	0000В6н	
DTP/External interrupt ch.6/ch.7	\triangle	×	#24	18н	FFFF9C _H	ICR06		
No		_	#25	19н	FFFF98 _H	ICD07	0000В7н	
No		_	#26	1Ан	FFFF94 _H	ICR07		
No		_	#27	1Вн	FFFF90 _H	IODOO	000000	
No		_	#28	1Сн	FFFF8C _H	ICR08	0000В8н	
No		_	#29	1Dн	FFFF88 _H	IODOO	000000	
PPG ch.0/ch.1	×	×	#30	1Ен	FFFF84 _H	ICR09	0000В9н	
No		_	#31	1F _H	FFFF80 _H	IOD40	000000	
PPG ch.2/ch.3	×	×	#32	20н	FFFF7C _H	ICR10	0000ВАн	
No	_	_	#33	21н	FFFF78 _H	ICD44	000000	
No		_	#34	22н	FFFF74 _H	ICR11	0000ВВн	
No	_	_	#35	23н	FFFF70 _H	ICD40	000000	
No		_	#36	24н	FFFF6C _H	ICR12	0000ВСн	
UART (Send completed) ch.0/ch.1	0	13	#37	25н	FFFF68 _H	ICD40	000000	
Extended serial I/O	×	9	#38	26н	FFFF64 _H	ICR13	0000ВДн	
UART(Reception completed) ch.0/ch.1	0	12	#39	27н	FFFF60 _H	ICR14	0000ВЕн	
Time-base timer	×	×	#40	28н	FFFF5C _H			V
Flash memory status	×	×	#41	29н	FFFF58 _H	ICD15	00000	
Delay interrupt output module	×	×	#42	2Ан	FFFF54 _H	ICR15	0000ВFн	Lov

(Continued)

- Available. El²OS stop function provided (The interrupt request flag is cleared by the interrupt clear signal. With a stop request).
- O: Available (The interrupt request flag is cleared by the interrupt clear signal).
- △ : Available when any interrupt source sharing ICR is not used.
- × : Unavailable
- *1: If the same level interrupt is output simultaneously, the lower interrupt factor of interrupt vector number has priority.
- *2: Ch.2 and ch.3 can be used in USB HOST operation.
- Notes: If the same interrupt control register (ICR) has two interrupt factors and the use of the El²OS is permitted, the El²OS is activated when either of the factors is detected. As any interrupt other than the activation factor is masked while the El²OS is running, it is recommended that you should mask either of the interrupt requests when using the El²OS.
 - The interrupt flag is cleared by the El²OS interrupt clear signal for the resource that has two interrupt factors in the same interrupt control register (ICR).
 - If a resource has two interrupt sources for the same interrupt number, both of the interrupt request flags are cleared by the μDMAC interrupt clear signal. Therefore, when you use either of two interrupt factors for the DMAC function, another interrupt function is disabled. Set the interrupt request permission bit to "0" in the appropriate resource, and take measures by software polling.

■ CONTENT OF USB INTERRUPTION FACTOR

USB interrupt factor	Details
USB function 1	End Point 0-IN, End Point 0-OUT
USB function 2	End Point 1-5 *
USB function 3	SUSP, SOF, BRST, WKOP, COHF
USB function 4	SPIT
USB HOST1	DIRQ, CHHIRQ, URIRQ, RWKIRQ
USB HOST2	SOFIRQ, CMPIRQ

^{*:} End Point 1 and 2 can be used in USB HOST operation.

■ USB

1. USB Function

The USB function is an interface supporting the USB (Universal Serial Bus) communications protocol.

Features of USB function

- Supports USB Full Speed
- Supports full speed (12 Mbps).
- The device status is auto-answer.
- Bit stripping, bit stuffing, and automatic generation and check of CRC5 and CRC16.
- Toggle check by data synchronization bit.
- Automatic response to all standard commands except Get/SetDescriptor and SynchFrame commands (these three commands can be processed the same way as the class vendor commands).
- The class vendor commands can be received as data and responded via firmware.
- Supports up to a maximum of six EndPoints (EndPoint0 is fixed to control transfer).
- Two built-in transfer data buffers for each end point (one IN buffer and one OUT buffer for end point 0).
- Supports automatic transfer mode for transfer data via DMA (except buffers for EndPoint0).

2. USB HOST

USB HOST provides minimal host operations required and is a function that enables data to be transferred between devices without PC intervention.

• Features of USB HOST

- Automatic detection of Low Speed/Full Speed transfer
- Low Speed/Full Speed transfer support
- · Automatic detection of connection and cutting device
- Reset sending function support to USB-bus
- Support of IN/OUT/SETUP/SOF token
- In-token handshake packet automatic transmission (excluding STALL)
- Handshake packet automatic detection at out-token
- Supports a maximum packet length of 256 bytes
- Error (CRC error/toggle error/time-out) various supports
- Wake-Up function support

Restrictions on USB HOST

• Restrictions on OSB NO		USB HOST
HUB support		· *
	Bulk transfer	0
T	Control transfer	0
Transfer	Interrupt transfer	0
	Isochronous transfer	×
Transferanced	Low Speed	0
Transfer speed	Full Speed	0
PRE packet support		×
SOF packet support		0
	CRC error	0
Free	Toggle error	0
Error	Time-out	0
	Maximum packet < receive data	0
Detection of connection a	and cutting of device	0
Transfer speed detection		0

○ : Supported× : Not supported

^{*:} Only supports full speed, and supports hubs up to one level.

■ SECTOR CONFIGURATION OF FLASH MEMORY

512 Kbits flash memory is located in FF_H bank in the CPU memory map.

Flash Memory CPU address Writer address *

		' 		
SA0 (4 Kbytes)	FF0000H	70000н		
SAU (4 Kbyles)	FF0FFFH	70FFFH		
CA1 (4 Kbytos)	FF1000H	71000н	논	
SA1 (4 Kbytes)	FF1FFFH	, 71FFFн	ower Bank	
CAO (4 Khytaa)	FF2000H	72000н	Wer	
SA2 (4 Kbytes)	FF2FFFH	72FFFH	2	
SA3 (4 Kbytes)	FF3000H	73000н		
SAS (4 Ruyles)	FF3FFFH	73FFFH		
SA4 (16 Kbytes)	FF4000H	74000н		
SA4 (10 Rbyles)	FF7FFFH	77FFFн		
SA5 (16 Kbytes)	FF8000H	78000н		
SAS (10 Rbytes)	FFBFFFH	' 7BFFFн		
SAG (4 Khytoo)	FFC000H	7С000н	녿	
SA6 (4 Kbytes)	FFCFFFH	7CFFFH	Jpper Bank	
SA7 (4 Kbytes)	FFD000H	7D000н	obei	
OA7 (4 Nbytes)	FFDFFFH	7DFFFH	<u> </u>	
SA8 (4 Kbytes)	FFE000H	7Е000н		
OAO (4 Noyles)	FFEFFFH	1 7EFFFн		
CAO (4Khytoo)	FFF000H	¦ 7F000н		
SA9 (4Kbytes)	FFFFFFH	7FFFFн		

^{*:} Flash memory writer address indicates the address equivalent to the CPU address when data is written to the flash memory using a parallel writer. Programming and erasing by the general-purpose parallel programmer are executed based on writer addresses.

■ ELECTRICAL CHARACTERISTICS

1. Absolute Maximum Ratings

Parameter	Symbol	Rating			Remarks	
Parameter	Syllibol	Min	Max	Unit	nemarks	
Power supply voltage*1	Vcc	Vss - 0.3	Vss + 4.0	V		
		Vss - 0.3	Vss + 4.0	V	*2	
Input voltage*1	Vı	Vss - 0.3	Vss + 6.0	٧	N-ch open-drain (Withstand voltage I/O of 5 V)*3	
		- 0.5	Vss + 4.5	V	USB I/O	
Output valtage*1	V	Vss - 0.3	Vss + 4.0	V	*2	
Output voltage*1	Vo	- 0.5	Vss + 4.5	V	USB I/O	
Maximum clamp current	I CLAMP	- 2.0	+2.0	mA	*4	
Total maximum clamp current	Σ ICLAMP	_	20	mA	*4	
"L" level maximum output	lol1	10 mA		mA	Other than USB I/O*5	
current	l _{OL2}	_	43	mA	USB I/O*5	
((1)) I = 1 = 1 = 1 = 1	lolav1	_	4	mA	*6	
"L" level average output current	lolav2	_	15/4.5	mA	USB-IO (Full speed/Low speed) *6	
"L" level maximum total output current	ΣΙοι	_	100	mA		
"L" level average total output current	Σ lolav	<u> </u>	50	mA	*7	
"H" level maximum output	Іон1	_	- 10	mA	Other than USB I/O*5	
current	І он2	_	- 43	mA	USB I/O*5	
(1) 12 11	Iонаv1	_	- 4	mA	*6	
"H" level average output current	lohav2	_	-15/-4.5	mA	USB-IO (Full speed/Low speed) *6	
"H" level maximum total output current	ΣІон	_	- 100	mA		
"H" level average total output current	ΣΙοнαν	_	- 50	mA	*7	
Power consumption	Pd	_	270	mW		
Operating temperature	TA	- 40	+ 85	°C		
Storage temperature	Tota	- 55	+ 150	°C		
Siorage temperature	Tstg	- 55	+ 125	°C	USB I/O	

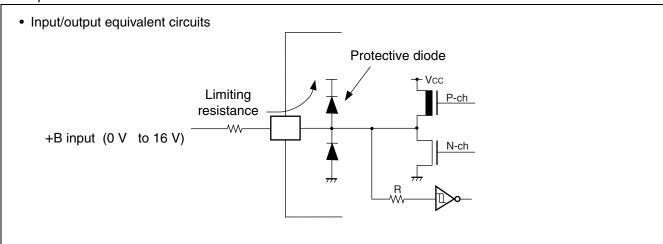
^{*1 :} The parameter is based on $V_{SS} = 0.0 \text{ V}$.

^{*2:} V_I and V_O must not exceed V_{CC} + 0.3 V. However, if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.

^{*3:} Applicable to pins: P60 to P67, UTEST

(Continued)

- *4: Applicable to pins: P00 to P07, P10 to P17, P20 to P27, P40 to P47, P50 to P54
 - Use within recommended operating conditions.
 - Use at DC voltage (current)
 - The +B signal should always be applied a limiting resistance placed between the +B signal and the microcontroller.
 - The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
 - Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the Vcc pin, and this may affect other devices.
 - Note that if a +B signal is input when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
 - Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the power-on reset.
 - Care must be taken not to leave the +B input pin open.
 - Note that analog system input/output pins other than P60 to P67, DVP, DVM, HVP, HVM, UTEST, HCON
- Sample recommended circuits:



- *5: A peak value of an applicable one pin is specified as a maximum output current.
- *6: The average output current specifies the mean value of the current flowing in the relevant single pin during a period of 100 ms.
- *7: The average total output current specifies the mean value of the currents flowing in all of the relevant pins during a period of 100 ms.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

2. Recommended Operating Conditions

(Vss = 0.0 V)

Parameter	Symbol	Va	lue	Unit	Remarks
Parameter	Symbol	Min	Max	Offic	nemarks
		3.0	3.6	V	At normal operation (When using USB)
Power supply voltage	Vcc	2.7	3.6	V	At normal operation (When not using USB)
		1.8	3.6	V	Hold state of stop operation
	VıH	0.7 Vcc	Vcc + 0.3	V	CMOS input pin
	V _{IHS1}	0.8 Vcc	Vcc + 0.3	V	CMOS hysteresis input pin
Input "H" voltage	V _{IHS2}	0.8 Vcc	Vss + 5.3	V	N-ch open-drain (Withstand voltage I/O of 5 V)*
	VIHM	Vcc - 0.3	Vcc + 0.3	V	MD pin input
	VIHUSB	2.0	Vcc + 0.3	V	USB pin input
	Vıl	Vss - 0.3	0.3 Vcc	V	CMOS input pin
Input "L" voltage	VILS	Vss - 0.3	0.2 Vcc	V	CMOS hysteresis input pin
Input L voltage	VILM	Vss - 0.3	Vss + 0.3	V	MD pin input
	VILUSB	Vss	0.8	V	USB pin input
Differential input sensitivity	VDI	0.2	_	V	USB pin input
Differential common mode input voltage range	Vсм	0.8	2.5	V	USB pin input
Operating	TA	- 40	+ 85	°C	When not using USB
temperature	IA	0	+ 70	°C	When using USB

^{*:} Applicable to pins: P60 to P67, UTEST

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure. No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

3. DC Characteristics

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

Dawan atau	Sym-	Dia nome	(VCC = 0.0 V		Value		11	Damaria.
Parameter	bol	Pin name	Conditions	Min	Тур	Max	Unit	Remarks
Output "H"	Vон	Output pins other than P60 to P67, HVP, HVM, DVP, DVM	Iон = −4.0 mA	Vcc - 0.5	_	Vcc	V	
		HVP, HVM, DVP, DVM	$R_L = 15 \text{ k}\Omega \pm 5\%$	2.8		3.6	٧	
Output "L" voltage	Vol	Output pins other than HVP, HVM, DVP, DVM	I _{OL} = 4.0 mA	Vss		Vss + 0.4	٧	
voltage		HVP, HVM, DVP, DVM	$R_L = 1.5 \text{ k}\Omega \pm 5\%$	0		0.3	٧	
Input leak current	Iı∟	Input pins other than P60 to P67, HVP, HVM, DVP, DVM	Vcc = 3.3 V, Vss < Vı < Vcc	- 10	_	+ 10	μΑ	
Current		HVP, HVM, DVP, DVM	_	- 5	_	+ 5	μΑ	
Pull-up resistance	RPULL	P00 to P07, P10 to P17	Vcc = 3.3 V, T _A = + 25 °C	25	50	100	kΩ	
Open drain output leak current	ILIOD	P60 to P67	_	_	0.1	10	μΑ	
			Vcc = 3.3 V, Internal frequency 24 MHz, At normal operating	_	55	65	mA	MB90F337
	Icc		At USB operating (USTP = 0)	_	50	60	mA	MB90337
	100		Vcc = 3.3 V, Internal frequency 24 MHz, At normal operating	_	50	60	mA	MB90F337
Power			At non-operating USB (USTP = 1)	_	45	55	mA	MB90337
supply current	Iccs	Vcc	Vcc = 3.3 V, Internal frequency 24 MHz, At sleep mode	_	25	40	mA	
	Істѕ		Vcc = 3.3 V, Internal frequency 24 MHz, At timer mode	_	3.5	10	mA	
	ICIS		Vcc = 3.3 V, Internal frequency 3 MHz, At timer mode	_	1.0	2.0	mA	
	Іссн		T _A = +25 °C, At stop mode		1	40	μΑ	

(Continued)

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

Parameter	Sym-	Pin name	Conditions		Value	Unit	Remarks	
raiailletei	bol Fill fame Conditions		Min	Тур	Max	Oilit	nemarks	
Input capacitance		Other than Vcc and Vss	_	_	5	15	pF	
Pull-up resistor	Rup	RST		25	50	100	kΩ	
Pull-down resistor	Rdown	MD2	Vcc = 3.0 V At T _A = +25 °C	25	50	100	kΩ	MB90337
USB I/O output impedance	/ LICD	DVP, DVM HVP, HVM	_	3		14	Ω	_

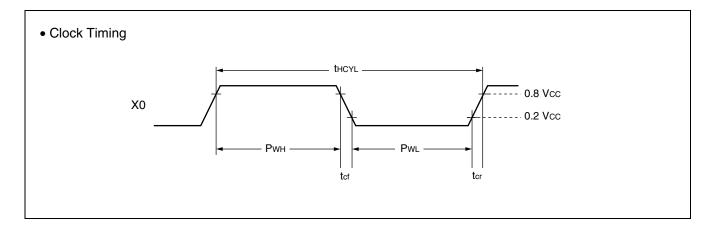
Note: P60 to P67 are N-ch open-drain pins usually used as CMOS.

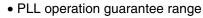
4. AC Characteristics

(1) Clock input timing

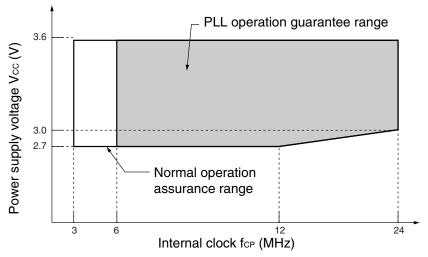
(Vcc = 3.3 V
$$\pm$$
 0.3 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

Parameter	Sym-	Pin		Value		Unit	Remarks
raiailletei	bol	name	Min	Тур	Max	Oilit	nemarks
Clock frequency	fсн	X0, X1	_	6	_	MHz	When oscillator is used
Clock frequency	ICH	Λυ, Λι	6		24	MHz	External clock input
Clock cycle time	thcyl	X0, X1	_	166.7		ns	When oscillator is used
Clock cycle time	L HCYL	Λυ, Λι	166.7		41.7	ns	External clock input
Input clock pulse width	Pwh PwL	Х0	10		_	ns	A reference duty ratio is 30% to 70%.
Input clock rise time and fall time	tcr tcf	X0		_	5	ns	At external clock
Internal operating clock frequency	fср	_	3		24	MHz	When main clock is used
Internal operating clock cycle time	t CP	_	42	_	333	ns	When main clock is used



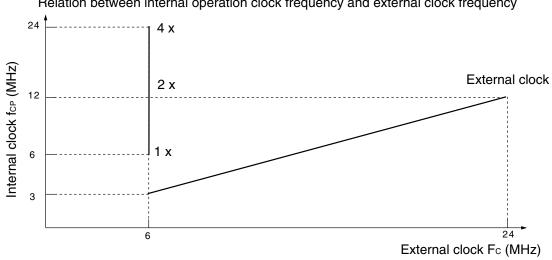


Relation between power supply voltage and internal operation clock frequency



Note: When the USB is used, operation is guaranteed at voltages between 3.0 V to 3.6 V.

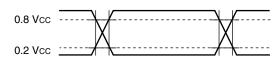
Relation between internal operation clock frequency and external clock frequency



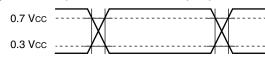
The AC standards provide that the following measurement reference voltages.

• Input signal waveform

Hysteresis input pin



Hysteresis input/other than MD input pin



• Output signal waveform

Output pin

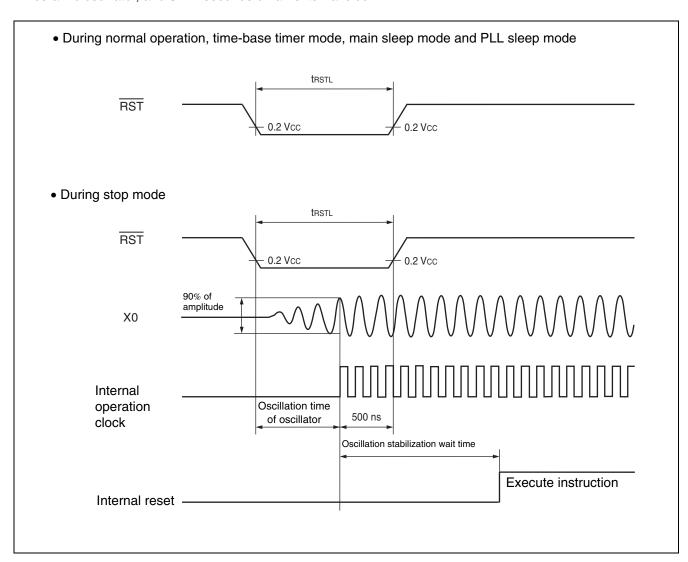


(2) Reset

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

Parameter	Sym-		Sym- Pin Conditions			Unit	Remarks	
raiailletei	bol	name	Conditions	Min	Max	Oilit	nemarks	
Reset input time	t RSTL	RST	_	500	_	ns	At normal operating, At time base timer mode, At main sleep mode, At PLL sleep mode	
				Oscillation time of oscillator* + 500 ns		μs	At stop mode	

*: Oscillation time of oscillator is the time that the amplitude reaches 90 %. It takes several milliseconds to several dozens of milliseconds on a crystal oscillator, several hundreds of microseconds to several milliseconds on a ceramic oscillator, and 0 milliseconds on an external clock.



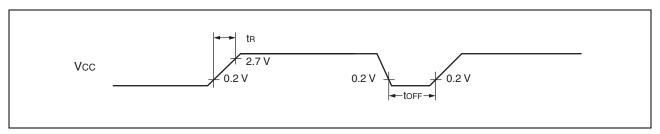
(3) Power-on reset

 $(V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}, \text{ Vss} = 0.0 \text{ V}, \text{ Ta} = -40 ^{\circ}\text{C} \text{ to } +85 ^{\circ}\text{C})$

Parameter	Symbol	Symbol Pin name		Val	lue	Unit	Remarks	
raiailletei	Syllibol	Fili lialile	Conditions	Min	Max	Oilit	nemarks	
Power supply rising time	t R	Vcc		0.05	30	ms		
Power supply shutdown time	toff	Vcc	_	1	_	ms	Waiting time until power-on	

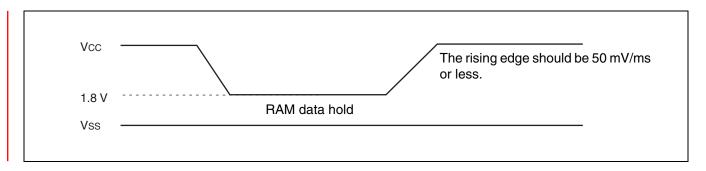
Notes: • Vcc must be lower than 0.2 V before the power supply is turned on.

- The above standard is a value for performing a power-on reset.
- In the device, there are internal registers which is initialized only by a power-on reset. When the initialization of these items is expected, turn on the power supply according to the standards.



Note: Sudden change of power supply voltage may activate the power-on reset function.

When changing the power supply voltage during operation as illustrated below, voltage fluctuation should be minimized so that the voltage rises as smoothly as possible. When raising the power, do not use PLL clock. However, if voltage drop is 1 V/s or less, use of PLL clock is allowed during operation.



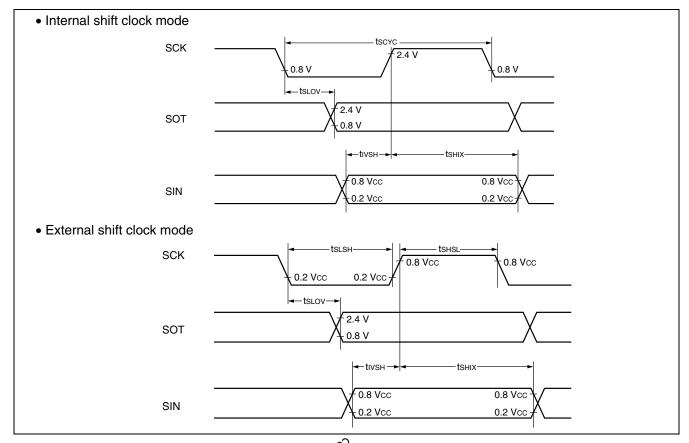
(4) UART0, UART1 I/O extended serial timing

 $(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, T_A = -40 ^{\circ}C to +85 ^{\circ}C)$

Parameter	Symbol	Pin name	Conditions	Value		Unit
Farameter	Syllibol	riii iiaiiie	Conditions	Min	Max	Oilit
Serial clock cycle time	tscyc	SCKx		8 tcp	_	ns
$SCK \downarrow \to SOT$ delay time	tsLov	SCKx SOTx	Internal shift clock	- 80	+ 80	ns
Valid SIN → SCK ↑	tıvsн	SCKx SINx	Mode output pin is $C_L = 80 \text{ pF} + 1 \text{ TTL}$	100	_	ns
SCK ↑ → valid SIN hold time	tsнıх	SCKx SINx		60	_	ns
Serial clock H pulse width	t shsl	SCKx, SINx		4 tcp	_	ns
Serial clock L pulse width	t slsh	SCKx, SINx		4 tcp	_	ns
$SCK \downarrow \to SOT$ delay time	tsLov	SCKx SOTx	External shift clock Mode output pin is	_	150	ns
Valid SIN → SCK ↑	tıvsн	SCKx SINx	C _L = 80 pF + 1 TTL	60	_	ns
SCK ↑ → valid SIN hold time	tsнıх	SCKx SINx		60	_	ns

Notes: • Above rating is the case of CLK synchronous mode.

- C_L is a load capacitance value on pins for testing.
- tcp is the machine cycle period (unit : ns) . Refer to "(1) Clock input timing".



(5) I2C timing

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, T_A = -40 °C to +85 °C)

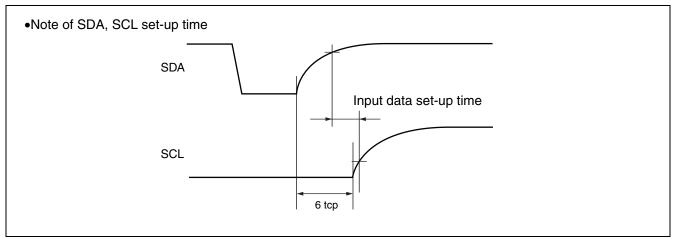
Parameter	Symbol Conditions		Val	ue	Unit
Parameter	Symbol	Conditions	Min	Max	Unit
SCL clock frequency	fscL		0	100	kHz
(Repeat) [start] condition hold time SDA $\downarrow \rightarrow$ SCL \downarrow	t HDSTA	Power-supply of external pull-up resistor			μs
SCL clock "L" width	tLOW	R = 1.2 kΩ, C = 50 pF* ²	4.7	_	μs
SCL clock "H" width	t HIGH	Power-supply of external pull-up resistor	4.0	_	μs
Repeat [start] condition setup time SCL $\uparrow \rightarrow$ SDA \downarrow	t susta	at 3.6 V R = 1.0 kΩ, C = 50 pF* ²	4.7		μs
Data hold time SCL $\downarrow \rightarrow$ SDA $\downarrow \uparrow$	thddat		0	3.45*3	μs
Data setup time		Power-supply of external pull-up resistor at 5.0 V fcp*1 \leq 20 MHz, R = 1.2 k Ω , C = 50 pF*2 Power-supply of external pull-up resistor at 3.6 V fcp*1 \leq 20 MHz, R = 1.0 k Ω , C = 50 pF*2	250*4	_	
SDA ↓↑→ SCL↑	t sudat	Power-supply of external pull-up resistor at 5.0 V fcp*1 > 20 MHz, R = 1.2 k Ω , C = 50 pF*2 Power-supply of external pull-up resistor at 3.6 V fcp*1 > 20 MHz, R = 1.0 k Ω , C = 50 pF*2	200*4	_	ns
[Stop] condition setup time SCL $\uparrow \rightarrow$ SDA \uparrow	tsusто	Power-supply of external pull-up resistor at 5.0 V	4.0		μs
Bus free time between [stop] condition and [start] condition	tвиs	R = 1.2 k Ω , C = 50 pF*2 Power-supply of external pull-up resistor at 3.6 V R = 1.0 k Ω , C = 50 pF*2	4.7	_	μs

^{*1 :} fcp is internal operating clock frequency. Refer to "(1) Clock input timing".

^{*2 :} R and C are pull-up resistance of SCL and SDA lines and load capacitance.

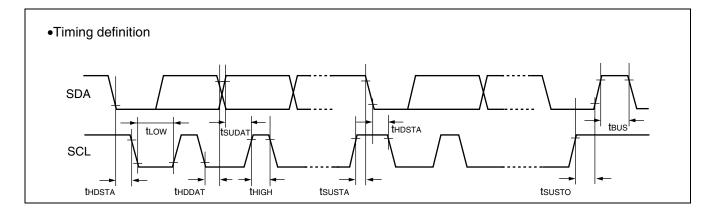
^{*3 :} The maximum thddat only has to be met if the device does not stretch the "L" width (tLow) of the SCL signal.

^{*4 :} Refer to "• Note of SDA, SCL set-up time".



Note: The rating of the input data set-up time in the device connected to the bus cannot be satisfied depending on the load capacitance or pull-up resistor.

Be sure to adjust the pull-up resistor of SDA and SCL if the rating of the input data set-up time cannot be satisfied.

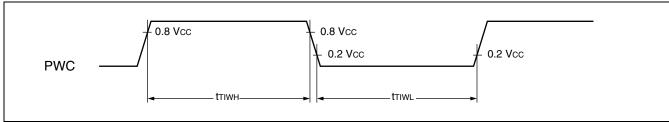


(6) Timer Input Timing

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, Ta = -40 °C to +85 °C)

Parameter	Symbol	Din name	in name Conditions		Pin name Conditions Value		lue	Unit
raiailletei	Symbol	riii iiaiiie	Conditions	Min	Max	Oille		
Input pulse width	tтıwн tтıwL	PWC	_	4 tcp	_	ns		

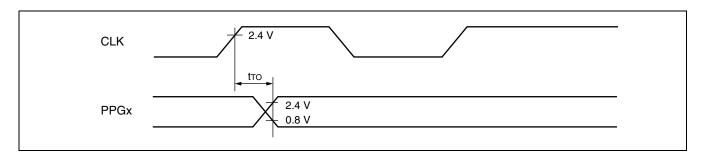
Note: tcp is the machine cycle period (unit: ns). Refer to "(1) Clock input timing".



(7) Timer output timing

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, Ta = -40 °C to +85 °C)

Parameter	Symbol	Pin name	Conditions	Value		Unit
Farameter	Syllibol	riii iiaiiie	Conditions	Min	Max	Oille
CLK ↑ → Tout change time PPG0 to PPG3 change time	t TO	PPGx		30	_	ns

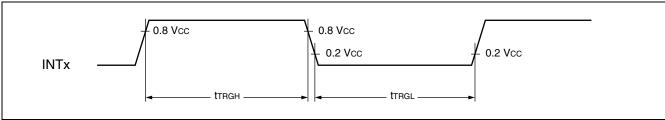


(8) Trigger Input Timing

 $(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, T_A = -40 ^{\circ}C to +85 ^{\circ}C)$

Parameter	Symbol	Pin name Conditions		Pin name Conditions Value		Value		Remarks
Farameter	Syllibol	Pili liaille	Conditions	Min	Max	Ollit	nemarks	
Input pulse width	t TRGH	INTx		5 tcp	_	ns	At normal operating	
Input puise width	t TRGL		_	1		μs	At Stop mode	

Note: tcp is the machine cycle period (unit: ns). Refer to "(1) Clock input timing".



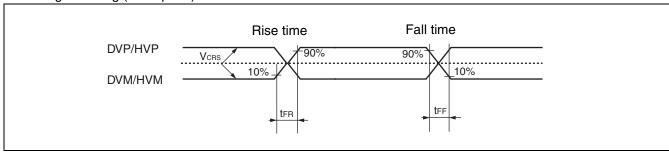
5. USB characteristics

(Vcc = 3.3 V \pm 0.3 V, Vss = 0.0 V, Ta = 0 °C to +70 °C)

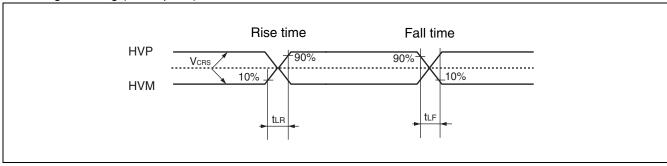
Parameter	Symbol	Sym-	Va	lue	Unit	Remarks
Parameter	Symbol	bol	Min	Max	Oilit	nemarks
	Input High level voltage	VIH	2.0	_	V	
Input	Input Low level voltage	VıL	_	0.8	V	
characteristics	Differential input sensitivity	VDI	0.2	_	V	
	Differential common mode range	Vсм	0.8	2.5	V	
	Output High level voltage	Vон	2.8	3.6	V	Іон = –200 μА
	Output Low level voltage		0.0	0.3	V	IoL = 2 mA
	Cross over voltage	Vcrs	1.3	2.0	V	
	Rise time	trr	4	20	ns	Full Speed
Output		tlr	75	300	ns	Low Speed
characteristics	Fall time	tff	4	20	ns	Full Speed
	raii iiiile	tlf	75	300	ns	Low Speed
	Dising/falling time matching	tпFM	90	111.11	%	(Tfr/Tff)
Rising/falling time matching		tпLM	80	125	%	(Tlr/Tlf)
	Output impedance		28	44	Ω	Including Rs = 27 Ω
Series resistance		Rs	25	30	Ω	Recommended value = 27Ω at using USB*

^{*:} Arrange the series resistance Rs values in order to set the impedance value within the output impedance ZSRV.

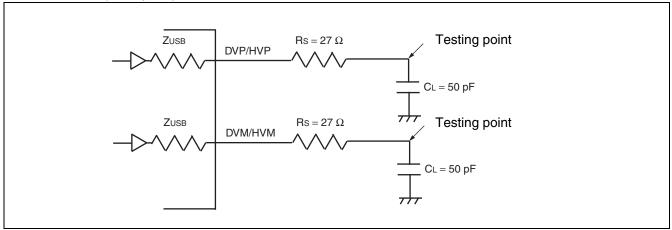
• Data signal timing (Full Speed)



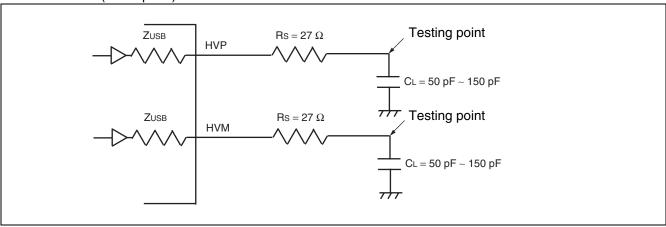
• Data signal timing (Low Speed)



• Load condition (Full Speed)



• Load condition (Low Speed)



6. Flash memory write/erase characteristics

Parameter	Condition	Value			Unit	Downsels	
Parameter	Condition	Min	Тур	Max	Unit	Remarks	
Sector erase time (4 Kbytes sector)		_	0.2	0.5	S	Excludes 00 _H programming prior to erasure.	
Sector erase time (16 Kbytes sector)	T _A = + 25 °C	_	0.5	7.5	S	Excludes 00 _H programming prior to erasure.	
Chip erase time	Vcc = 3.0 V	_	2.6	_	S	Excludes 00 _H programming prior to erasure.	
Word (8 bits width) programming time		_	16	3600	μs	Except for over head time of system	
Program/erase cycle	_	10000			cycle		
Flash data retention time	Average T _A = +85 °C	20	_	_	year	*	

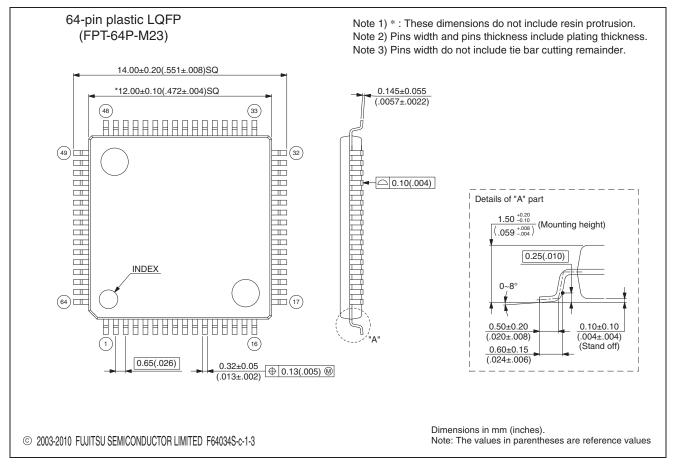
 $^{^*}$: This value comes from the technology qualification. (using Arrhenius equation to translate high temperature measurements into normalized value at + 85 $^{\circ}$ C)

■ ORDERING INFORMATION

Part number	Package	Remarks
MB90F337PMC MB90337PMC	64-pin plastic LQFP (FPT-64P-M23)	
MB90V330ACR	299-pin ceramic PGA (PGA-299C-A01)	For evaluation

■ PACKAGE DIMENSION

64-pin plastic LQFP	Lead pitch	0.65 mm
	Package width × package length	12.0 × 12.0 mm
	Lead shape	Gullwing
	Sealing method	Plastic mold
	Mounting height	1.70 mm MAX
	Weight	0.47 g
(FPT-64P-M23)	Code (Reference)	P-LQFP64-12×12-0.65



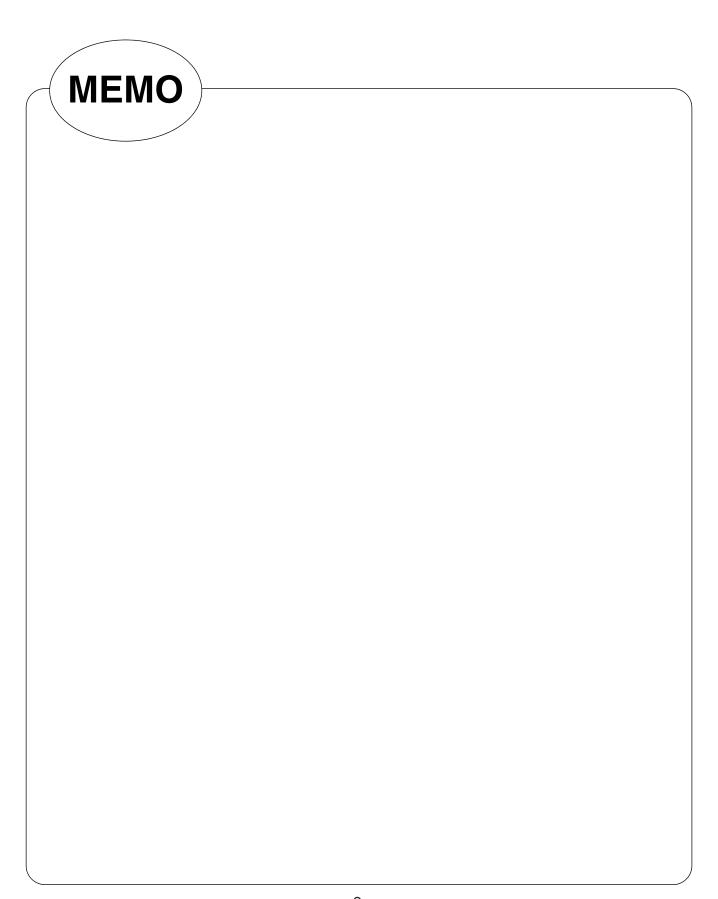
Please check the latest package dimension at the following URL. http://edevice.fujitsu.com/package/en-search/

■ MAIN CHANGES IN THIS EDITION

Page	Section	Change Results
35	■ ELECTRICAL CHARACTERISTICS 4.AC Characteristics (3) Power-on reset	Corrected as follows; Voltage of RAM data hold: 3.0 V \rightarrow 1.8 V

The vertical lines marked in the left side of the page show the changes.





FUJITSU SEMICONDUCTOR LIMITED

Nomura Fudosan Shin-yokohama Bldg. 10-23, Shin-yokohama 2-Chome, Kohoku-ku Yokohama Kanagawa 222-0033, Japan

Tel: +81-45-415-5858 http://jp.fujitsu.com/fsl/en/

For further information please contact:

North and South America

FUJITSU MICROELECTRONICS AMERICA, INC. 1250 E. Arques Avenue, M/S 333
Sunnyvale, CA 94085-5401, U.S.A.
Tel: +1-408-737-5600 Fax: +1-408-737-5999
http://www.fma.fujitsu.com/

Europe

FUJITSU MICROELECTRONICS EUROPE GmbH Pittlerstrasse 47, 63225 Langen, Germany Tel: +49-6103-690-0 Fax: +49-6103-690-122 http://emea.fujitsu.com/microelectronics/

Korea

FUJITSU MICROELECTRONICS KOREA LTD. 206 Kosmo Tower Building, 1002 Daechi-Dong, Gangnam-Gu, Seoul 135-280, Republic of Korea Tel: +82-2-3484-7100 Fax: +82-2-3484-7111 http://kr.fujitsu.com/fmk/

Asia Pacific

FUJITSU MICROELECTRONICS ASIA PTE. LTD. 151 Lorong Chuan, #05-08 New Tech Park 556741 Singapore Tel: +65-6281-0770 Fax: +65-6281-0220 http://www.fmal.fujitsu.com/

FUJITSU MICROELECTRONICS SHANGHAI CO., LTD. Rm. 3102, Bund Center, No.222 Yan An Road (E), Shanghai 200002, China Tel: +86-21-6146-3688 Fax: +86-21-6335-1605

http://cn.fujitsu.com/fmc/

FUJITSU MICROELECTRONICS PACIFIC ASIA LTD. 10/F., World Commerce Centre, 11 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: +852-2377-0226 Fax: +852-2376-3269

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